

--Fig. 3 shows a basic configuration of the holder section 3 described above. On the top is a cross-sectional view of the holder section 3, while on the bottom is a top view of the holder section 3. The cross-sectional view shown in Fig. 3 is taken along the dash line A-A' in the upper view. As shown in Fig. 3, the holder section 3 has the inner mask 11 for fixing the optical disk substrate 1 at a position close to a central point of the optical disk substrate 1 and the outer mask for fixing the optical disk substrate 1 at a position close to a periphery section of the optical disk substrate 1. Both the inner mask 11 and outer mask 12 cover a portion of the optical disk substrate 1, and fix the optical disk substrate 1 holding the optical disk substrate between it and an upper surface of the holder section 3. Because of this configuration, of a surface of the optical disk substrate 1, only portions [no] not fixed by the inner mask 11 and outer mask 12 is a film-formed section S. In the first embodiment, the radius of the inner mask 11 is 20 mm, while the radius of the outer mask is 59 mm.--

Page 56, beginning at line 5, to page 57, line 4, please replace the paragraph as follows:

--Fig. 27 shows a general configuration in the twelfth embodiment of the present invention. In this embodiment, a silicon rubber member [5] 405 with a width H is provided in the edge section 401e having the configuration used in the ninth embodiment described above and shown in Fig. 18. The width H is defined herein as a length of the silicon rubber member [5] 405 in the radial direction of the substrate 404 as shown in Fig. 27. With the configuration shown in Fig. 27, samples of substrate holder No. 22 to No. 27 are manufactured as shown in Fig. 26, and firm formation is performed on each of the samples under the same conditions as those in the eleventh embodiment, and assessment is carried out. As shown in Fig. 26, with the configuration according to this embodiment, a warping amount of a substrate can be suppressed to around 100 μ m, and also damages to a substrate